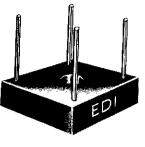
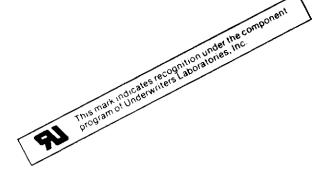
## SINGLE-PHASE FULL WAVE BRIDGE

6.0 AMPERES HEAT SINK MOUNTING 3.0 AMPERES FOR P.C. BOARD MOUNTING





## PP SERIES

PRV/leg	50∨	100∨	200V	400V	600V	800∨	1000∨
Type No.	PP 05	PP 10	PP 20	PP 40	PP 60	PP 80	PP100

## ELECTRICAL CHARACTERISTICS PER LEG (at T<sub>A</sub> = 25°C Unless Otherwise Specified)

Max. Forward Voltage Drop, V <sub>F</sub> = 1.2V @ I <sub>F</sub> =	2.0	Amp
Max. DC Reverse Current @ PRV and 25°C, IR	10.0	μА
Max. Peak Surge Current, IFSM (8.3 ms)	100	Amp
Ambient Operating Temperature Range, TA	-55 to +150	oC
Storage Temperature Range, T <sub>stg</sub>	-55 to +150	°C
Thermal Resistance(Total Bridge), R <sub>θj-c</sub>	6.0typ.	°C/W

NOTE Maximum lead and terminal temperature for soldering, 3/8 inch from case, 5 seconds at 250°C.

EDI reserves the right to change these specifications at any time without notice.

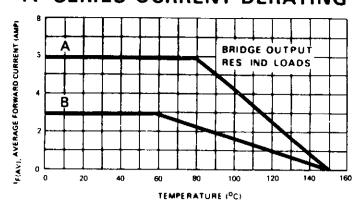


ELECTRONIC DEVICES, INC.

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## Figure 1 PP SERIES CURRENT DERATING



A = CASE TEMPERATURE, HEAT SINK MOUNTED B = AMBIENT TEMPERATURE

Figure 2
NON-REPETITIVE SURGE CURRENT

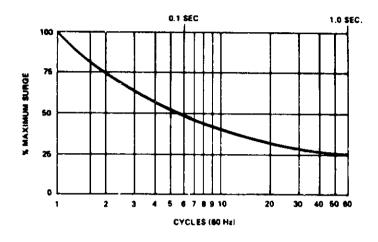
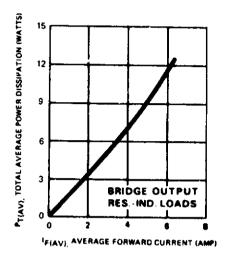
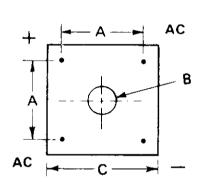
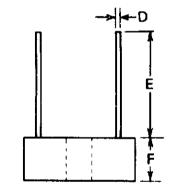


Figure 3
POWER DISSIPATION



PP SERIES MECH. OUTLINE





LTR	INCHES	MILLIMETERS		
Α	.411441	10.44-11.20		
В	.137167 DIA	3.48-4.24 DIA		
С	.590610	14.99 – 15.49		
D	.038042	.97 – 1.07		
E	.750 MIN	19.05 MIN		
F	.300 MAX	7.62 MAX		

NOTE: 1. A thin film of silicone thermal compound is recommended between the bridge case and mounting surface for improved thermal conduction.